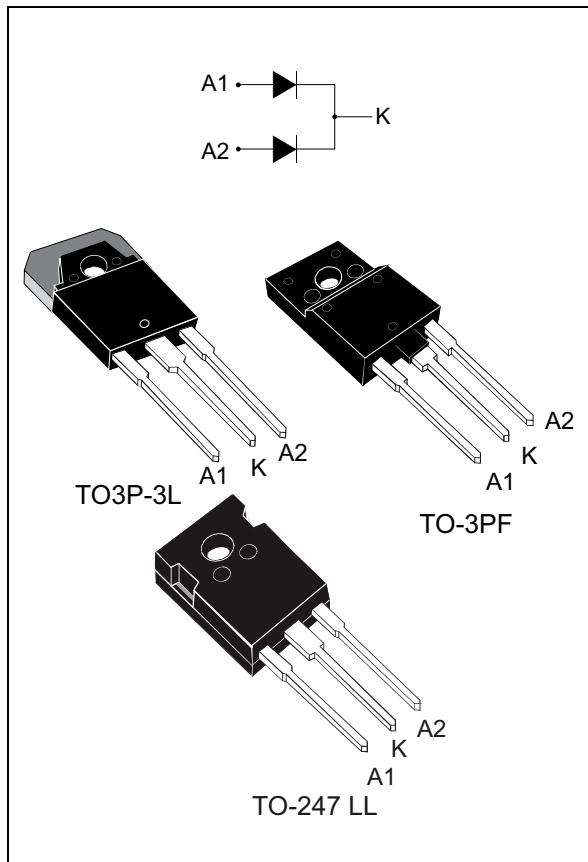


Turbo 2 ultrafast high voltage rectifier

Datasheet – production data



Description

The STTH30AC06C uses ST Turbo 2 600 V technology. It is suited as boost diode specially for use in air conditioning equipment as continuous mode interleaved power factor correction.

Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	2 x 15A
V_{RRM}	600 V
t_{rr} (typ)	40 ns
V_F (typ)	1.15 V
T_j	175 °C

Features

- Ultrafast switching
- Low reverse current
- Low thermal resistance
- Reduces switching and conduction losses
- Insulated package TO-3PF:
 - Insulated voltage: 2500 V_{DC}

1 Characteristics

Table 2. Absolute ratings (limiting values per diode at 25 °C, unless otherwise specified)

Symbol	Parameter		Value	Unit
V _{RRM}	Repetitive peak reverse voltage		600	V
I _{F(RMS)}	Forward rms current		30	A
I _{F(AV)}	Average forward current		Per diode	15
			Per device	30
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms sinusoidal	140	A
T _{stg}	Storage temperature range		-65 to +175	°C
T _j	Maximum operating junction temperature		175	°C

Table 3. Thermal parameters

Symbol	Parameter		Value	Unit
R _{th(j-c)}	Junction to case (TO3P-3L, TO247 LL)	Per diode	1.5	°C/W
		Total	0.85	
R _{th(c)}	Coupling (TO3P-3L, TO247 LL)		0.2	
R _{th(j-c)}	Junction to case (TO-3PF)	Per diode	3.5	°C/W
		Total	2.7	
R _{th(c)}	Coupling (TO-3PF)		1.9	

Table 4. Static electrical characteristics (per diode)

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
I _R ⁽¹⁾	Reverse leakage current	T _j = 25 °C	V _R = V _{RRM}	-		10	μA
		T _j = 150 °C		-	40	400	
V _F ⁽²⁾	Forward voltage drop	T _j = 25 °C	I _F = 15 A	-		1.95	V
		T _j = 150 °C		-	1.15	1.45	
		T _j = 25 °C	I _F = 30 A	-		2.25	
		T _j = 150 °C		-	1.42	1.8	

1. Pulse test: t_p = 5 ms, δ < 2%
2. Pulse test: t_p = 380 μs, δ < 2%

To evaluate the conduction losses use the following equation:

$$P = 1.1 \times I_{F(AV)} + 0.023 I_{F(RMS)}^2$$

Table 5. Dynamic characteristics (per diode)

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
t_{rr}	Reverse recovery time	$T_j = 25^\circ\text{C}$	$I_F = 0.5 \text{ A}, I_{rr} = 0.25 \text{ A}, I_R = 1 \text{ A}$	-		30	ns
			$I_F = 1 \text{ A}, V_R = 30 \text{ V}, dI_F/dt = 50 \text{ A}/\mu\text{s}$	-	40	55	
I_{RM}	Reverse recovery current	$T_j = 125^\circ\text{C}$	$I_F = 15 \text{ A}, V_R = 400 \text{ V}, dI_F/dt = 100 \text{ A}/\mu\text{s}$	-	4	5.5	A
t_{fr}	Forward recovery time	$T_j = 25^\circ\text{C}$	$I_F = 15 \text{ A}, V_{FR} = 1.9 \text{ V}, dI_F/dt = +100 \text{ A}/\mu\text{s}$	-		100	ns
V_{FP}	Forward recovery voltage			-	2.5		V

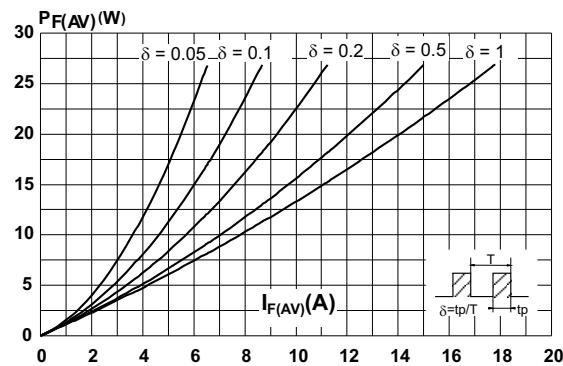
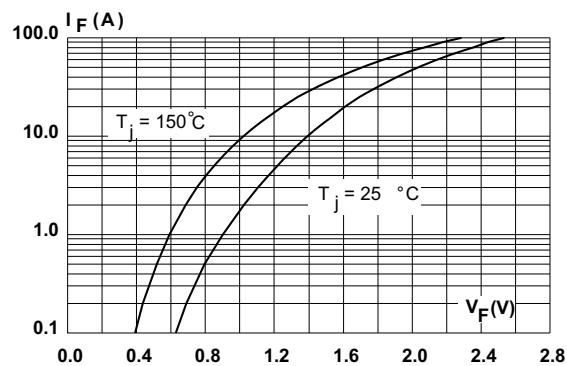
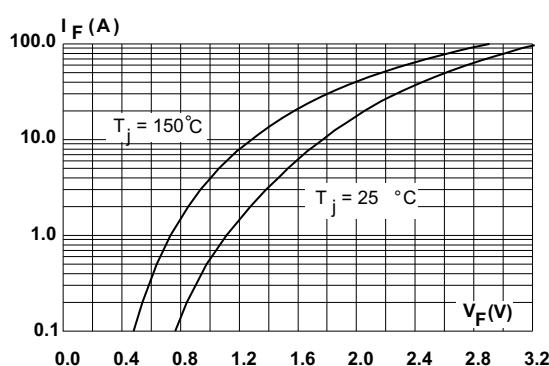
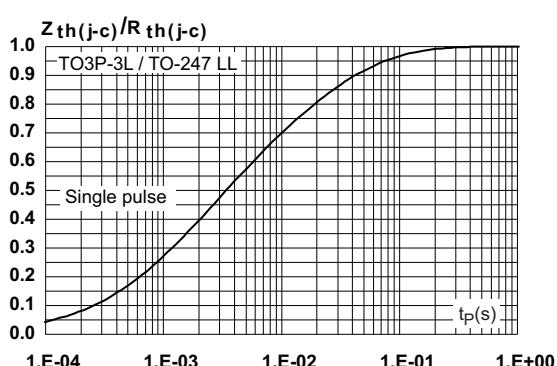
Figure 1. Average forward power dissipation versus average forward current (per diode)**Figure 2. Forward voltage drop versus forward current (typical values, per diode)****Figure 3. Forward voltage drop versus forward current (maximum values, per diode)****Figure 4. Relative variation of thermal impedance, junction to case, versus pulse duration (TO3P-3L, TO247 LL)**

Figure 5. Relative variation of thermal impedance, junction to case, versus pulse duration (TO-3PF)

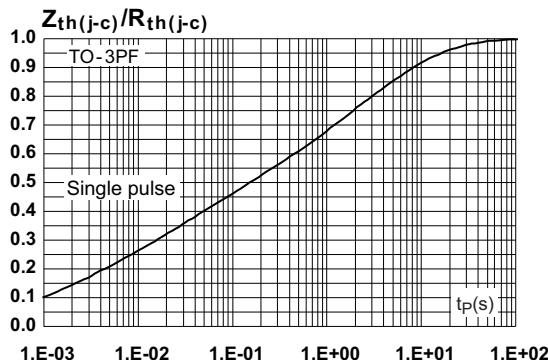


Figure 6. Peak reverse recovery current versus dI_F/dt (typical values, per diode)

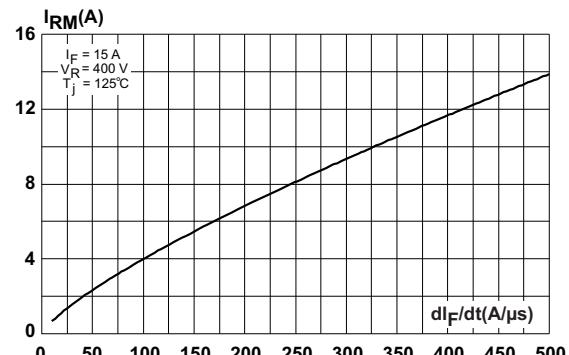


Figure 7. Reverse recovery time versus dI_F/dt (typical values, per diode)

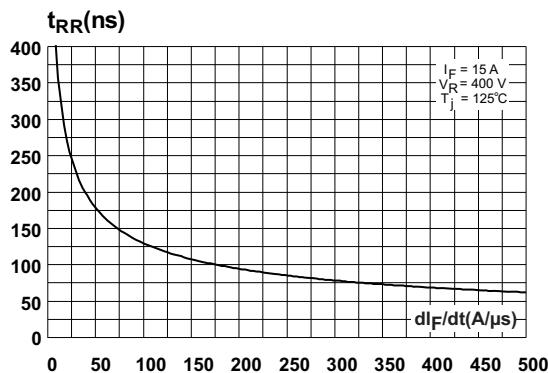


Figure 8. Reverse recovery charges versus dI_F/dt (typical values, per diode)

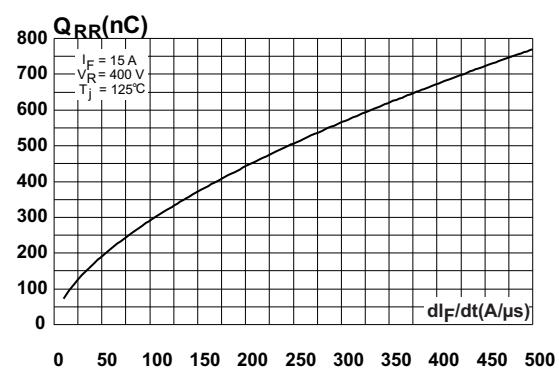


Figure 9. Reverse recovery softness factor versus dI_F/dt (typical values, per diode)

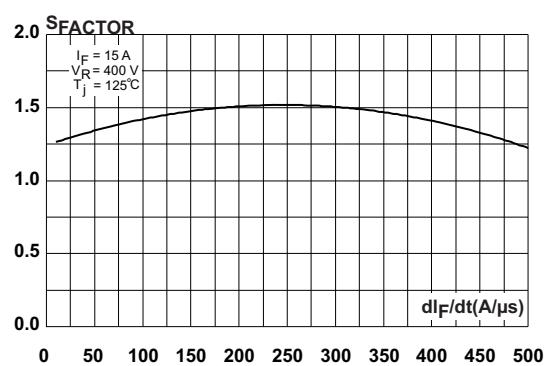


Figure 10. Relative variations of dynamic parameters versus junction temperature

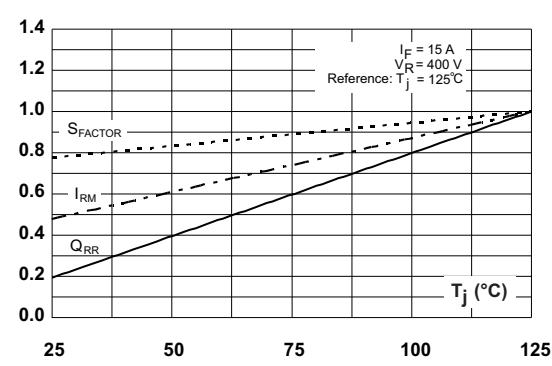


Figure 11. Transient peak forward voltage versus dI_F/dt (typical values, per diode)

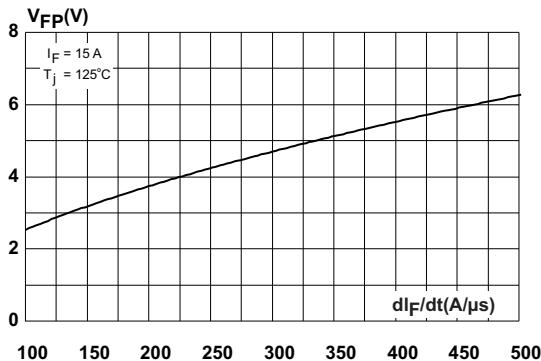


Figure 12. Forward recovery time versus dI_F/dt (typical values, per diode)

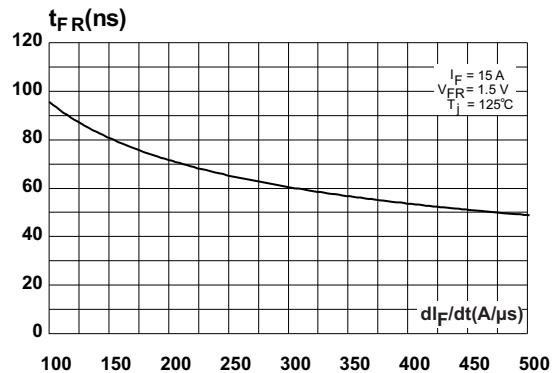
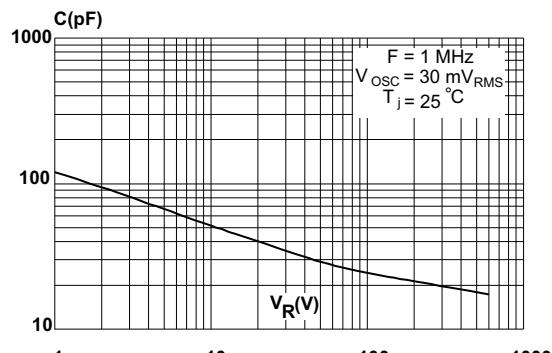


Figure 13. Junction capacitance versus reverse voltage applied (typical values, per diode)



2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque (TO-3PF): 0.4 to 0.6 N·m
- Maximum torque value (TO-247 LL): 1.0 N·m

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ECOPACK® is an ST trademark.

2.1 TO3P-3L package information

Figure 14. TO3P-3L package outline

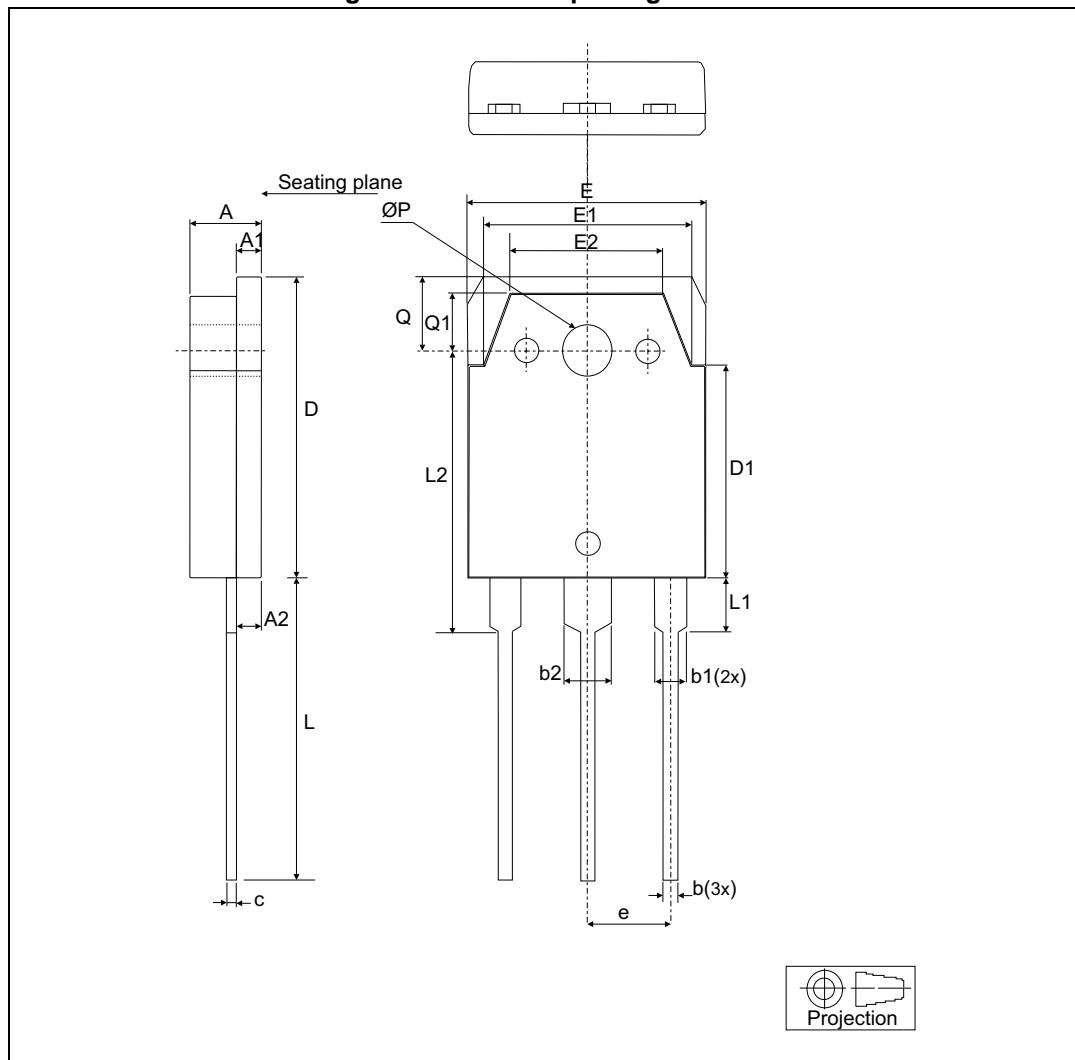


Table 6. TO3P-3L package mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.6		5	0.18		0.19
A1	1.45	1.5	1.65	0.05	0.06	0.06
A2	1.20	1.40	1.60	0.04	0.05	0.06
b	0.80	1	1.20	0.03	0.04	0.05
b1	1.80		2.20	0.07		0.08
b2	2.80		3.20	0.11		0.12
c	0.55	0.60	0.75	0.02	0.02	0.03
D	19.70	19.90	20.10	0.77	0.78	0.79
D1		13.90			0.54	
E	15.40		15.80	0.60		0.62
E1		13.60			0.53	
E2		9.60			0.38	
e	5.15	5.45	5.75	0.20	0.21	0.22
L	19.50	20	20.50	0.76	0.78	0.80
L1		3.50			0.14	
L2	18.20	18.40	18.60	0.71	0.72	0.73
ØP	3.10		3.30	0.12		0.13
Q		5			0.19	
Q1		3.80			0.15	

2.2 TO-3PF package information

Figure 15. TO-3PF package outline

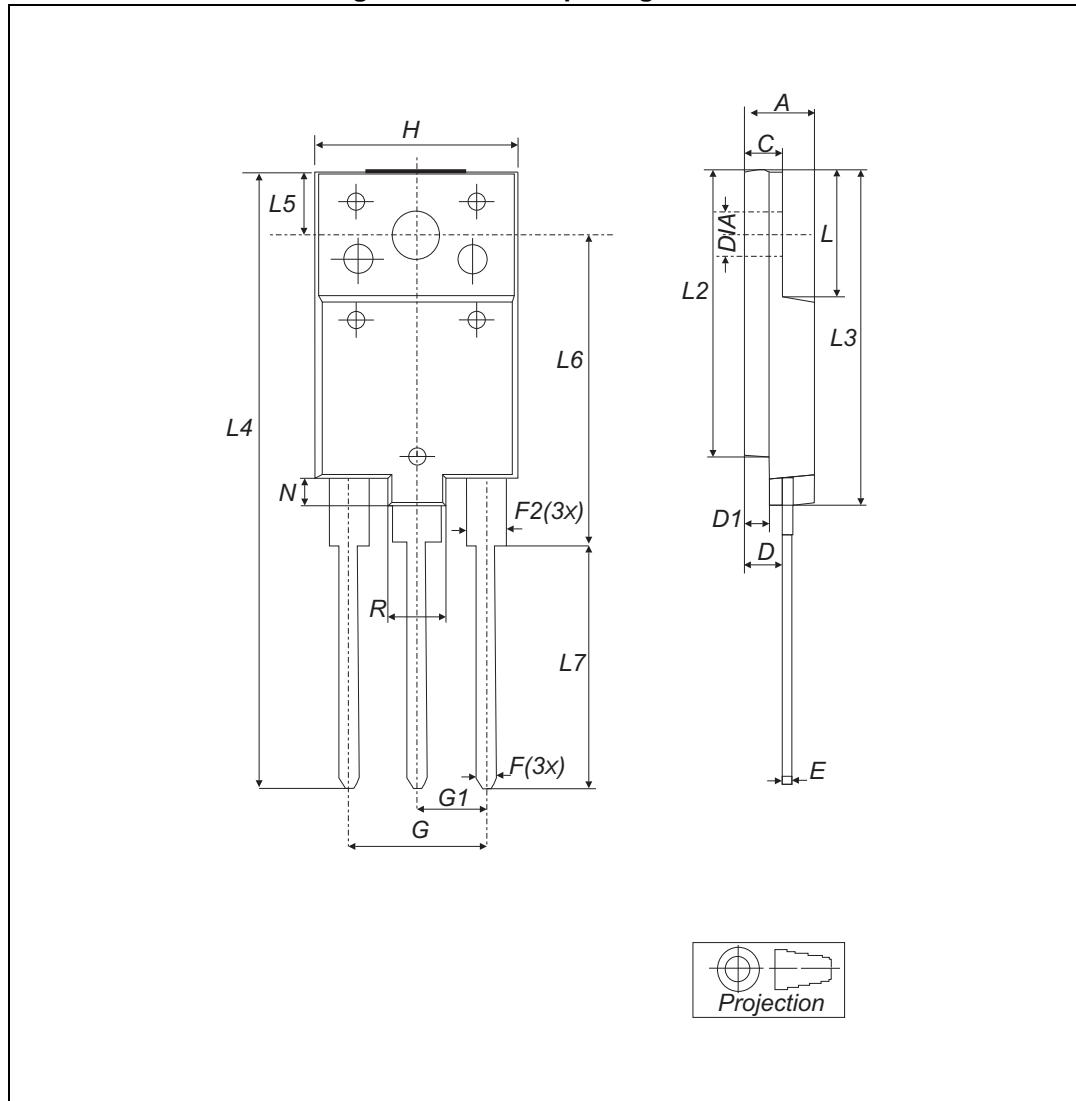


Table 7. TO-3PF mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	5.30		5.70	0.2		0.22
C	2.80		3.20	0.11		0.12
D	3.10		3.50	0.12		0.13
D1	1.80		2.20	0.07		0.08
E	0.80		1.10	0.03		0.04
F	0.65		0.95	0.025		0.037
F2	1.80		2.20	0.07		0.08
G	10.30		11.50	0.40		0.45
G1		5.45			0.21	
H	15.30		15.70	0.60		0.61
L	9.80	10	10.20	0.38	0.39	0.40
L2	22.80		23.20	0.89		0.91
L3	26.30		26.70	1.03		1.05
L4	43.20		44.40	1.70		1.74
L5	4.30		4.70	0.16		0.18
L6	24.30		24.70	0.95		0.97
L7	14.60		15	0.57		0.59
N	1.80		2.20	0.07		0.08
R	3.80		4.20	0.14		0.16
Dia	3.40		3.80	0.13		0.15

2.3 TO-247 LL package information

Figure 16. TO-247 LL package outline

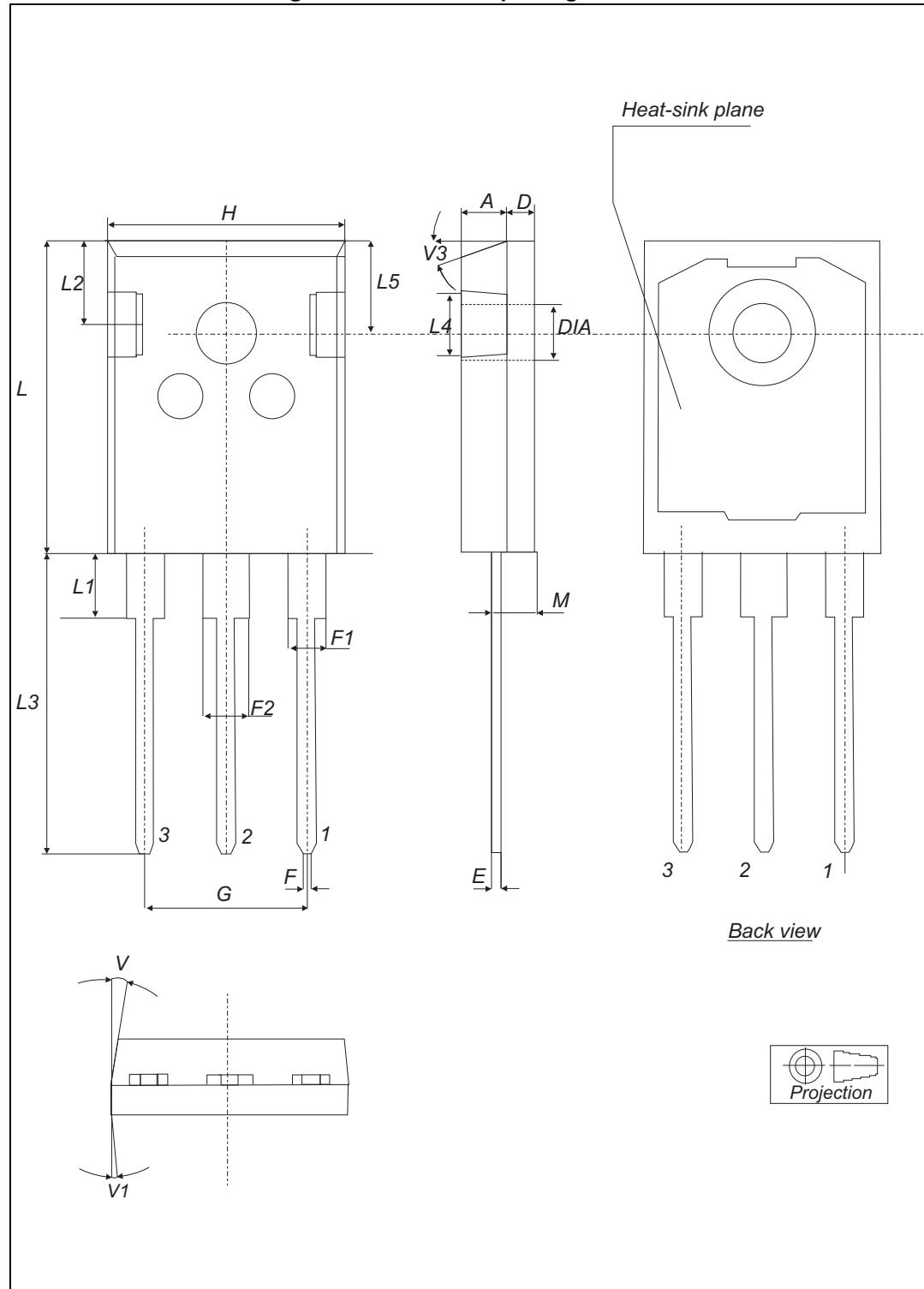


Table 8. TO-247 LL mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ	Max.
A	4.90		5.15	0.192		0.202
D	1.85		2.10	0.072		0.082
E	0.55		0.67	0.021		0.026
F	1.07		1.32	0.042		0.051
F1	1.90		2.38	0.074		0.093
F2	2.87		3.38	0.11		0.133
G	10.90 BSC			0.429 BSC		
H	15.77		16.02	0.62		0.63
L	20.82		21.07	0.81		0.82
L1	4.16		4.47	0.163		0.175
L2	5.49		5.74	0.216		0.225
L3	20.05		20.30	0.789		0.799
L4	3.68		3.93	0.144		0.154
L5	6.04		6.29	0.237		0.247
M	2.25		2.55	0.088		0.10
V		10°			10°	
V1		3°			3°	
V3		20°			20°	
Ø	3.55		3.66	0.139		0.143

3 Ordering information

Table 9. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STTH30AC06CP	STTH30AC06CP	TO3P-3L	5.26	30	Tube
STTH30AC06CPF	TH30AC06C	TO-3PF	5.6	30	Tube
STTH30AC06CWL	STTH30AC06CWL	TO-247 LL	4.36	30	Tube

4 Revision history

Table 10. Document revision history

Date	Revision	Changes
13-Nov-2013	1	First release.
25-Jun-2015	2	Update of cover page and Table 7 . Format updated to current standard.
01-Jul-2015	3	Updated Features .

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